

Apparatus for sealing a semiconductor device utilizing a release film

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Inventor: MIYAGAWA TSUTOMU (JP); AOKI KUNIHIRO (JP); KODAMA MASAHIRO (JP); MIYAJIMA FUMIO (JP)

Applicant: APIC YAMADA CORP (JP)

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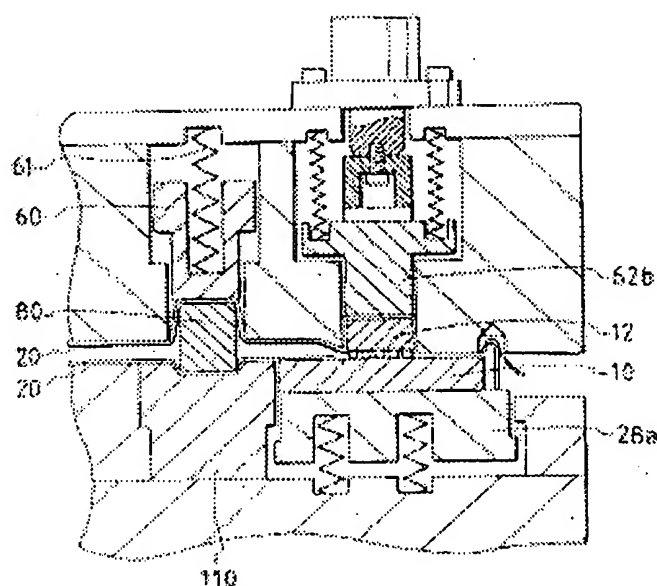
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Abstract of US6459159

A resin sealing method for sealing a joining portion between a semiconductor chip 12 and a substrate 10 by filling a underfilled portion of a molded piece 40 in which a semiconductor chip is mounted on a substrate with solder bumps studded therebetween with sealing resin 14 by a transfer molding process, the method being characterized in that when the molded piece 40 is clamped with a mold of a transfer molding machine, the perimeter of the underfilled portion, except the end of a gate continuous to the underfilled portion, is closed with a release film 20, and in a state that the perimeter of the underfilled portion is closed, the sealing resin 14 having been supplied to a pot 42 provided in the mold is fed under pressure to the underfilled portion, to thereby fill the underfilled portion.



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